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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-14 (canceled).

Claim 15 (previously presented): A cavity-down ball grid array package comprising:

- a flexible circuit tape including a flexible tape laminated to a conductor layer, the flexible circuit tape having an aperture therein;

- a thermally conductive heat spreader directly fixed to a first surface of the flexible circuit tape, the heat spreader having a cavity aligned with the aperture of the flexible circuit tape;

- a semiconductor die mounted to the heat spreader, in a die-down configuration in said cavity;

- a thermally conductive die adapter fixed to said semiconductor die such that a portion of said die adapter protrudes from said cavity;

- a plurality of wire bonds connecting said semiconductor die to bond sites on said second surface of said flexible circuit tape;

- an encapsulating material encapsulating said semiconductor die and said wire bonds; and

- a plurality of solder balls disposed on a second surface of the flexible circuit tape, in the form of a ball grid array,

- wherein said die adapter comprises a plurality of thermally conductive die adapter portions fixed side-by-side on said semiconductor die.

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Claim 16 (previously presented): The cavity-down ball grid array package according to claim 15, wherein said thermally conductive die adapter comprises a plurality of thermally conductive die adapter portions stacked on said semiconductor die.

Claim 17 (previously presented): The cavity-down ball grid array package according to claim 15, further comprising wire bonds connecting said semiconductor die to said die adapter.

Claim 18 (previously presented): The cavity-down ball grid array package according to claim 15, further comprising wire bonds connecting said semiconductor die to said heat spreader.

Claim 19 (previously presented): The cavity-down ball grid array package according to claim 15, further comprising wire bonds connecting said heat spreader to said die adapter.

Claim 20 (previously presented): The cavity-down ball grid array package according to claim 15, further comprising wire bonds connecting said flexible circuit tape to said die adapter.

Claim 21 (previously presented): The cavity-down ball grid array package according to claim 15, wherein said die adapter protrudes from said encapsulating material such that at least a surface of said die adapter is exposed.

Claim 22 (previously presented): The cavity-down ball grid array package according to claim 16, wherein one portion of said die adapter is a solid ground.

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Claim 23 (previously presented): The cavity-down ball grid array package according to claim 16, wherein one portion of said die adapter is a solid power.